

PATENTS
112055-0040
17732-38560

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re The Application of:
David Chong et al.

Serial No.: 09/823,600

Filed: March 30, 2001

For: PACKAGING SYSTEM FOR
DIE-UP CONNECTION OF A
DIE-DOWN ORIENTED INTE-
GRATED CIRCUIT

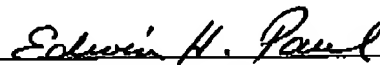
Examiner: Andujar, Leonardo

Art Unit: 2826

Cesari and McKenna, LLP
88 Black Falcon Avenue
Boston, MA 02210
July 15, 2004

CERTIFICATE OF TRANSMISSION

I hereby certify that the following paper is being facsimile transmitted to the Patent and Trademark Office on July 16, 2004. 703-872-9306


Edwin H. Paul

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

DECLARATION UNDER C.F.R. 1.132 OF DOUGLAS DOLAN

I, Douglas Dolan, being duly sworn do hereby state that I am an Employee of Fairchild Semiconductor corporation of South Portland, Maine, the owner of the above patent application.

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My title is Patent Engineer, and I am intimately involved Fairchild's operations regarding intellectual property, in particular, patents and pending applications.

I am a member of the Patent Committee where decisions are made on applying for patents. These decisions have many aspects but most important are those inventions that promise, among other things, to decrease cost to manufacture. The present application is an important invention covering a product that is in high volume production and that is providing substantial savings for the company.

I am well aware of the present application and the product line directly affected by this application. I have retrieved some production quantity numbers that support the original decision to file for a patent. The decision to go forward with the present application was motivated by the prospects of eliminating an IC package type from our product line. In this particular case the economics of eliminating an IC package type at the cost of a substrate weighed heavily in favor of the substrate. This decision has been borne out in the market place and promises to have a greater effect in the near future.

To date the number of devices produced using the substrate cross over scheme that allows one IC package to accept either a die up die or a die down die mounted to the inventive substrate is approaching 200 million units. Moreover, we will produce about 200 million units this year with increases over the next four years of about 25% per year.

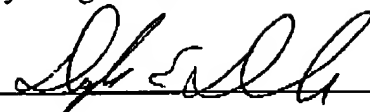
Needless to say, this is an important product and our competitive edge afforded by a patent covering this invention is very important. Our competitors continue to not realize the cost advantages of the invention.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 19 of the United States Code, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this verified statement is directed.

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Sworn and ascribed to by Douglas Dolan

Respectfully submitted,



Date: 7/15/04